2SD1273(A)

Rev.F Mar.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

TO-220F NPN Silicon NPN transistor in a TO-220F Plastic Package.

/ Features

h_{FE}

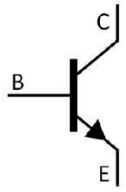
High h_{FE}, good linearity of h_{FE}.

/ Applications

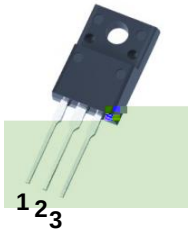
h_{FE}

Power amplifier with high forward current transfer ratio applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

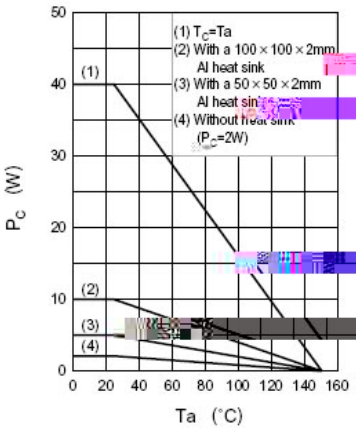
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	Q	P	O
h_{FE} Range	500 1000	800 1500	1200 2500

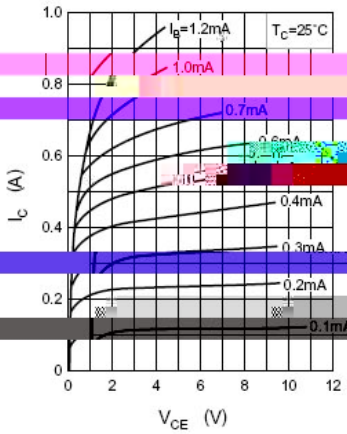
Parameter	Symbol		Rating	Unit
Collector to Base Voltage	V_{CBO}	2SD1273	80	V
		2SD1273A	100	
Collector to Emitter Voltage	V_{CEO}	2SD1273	60	

/ Electrical Characteristic Curve

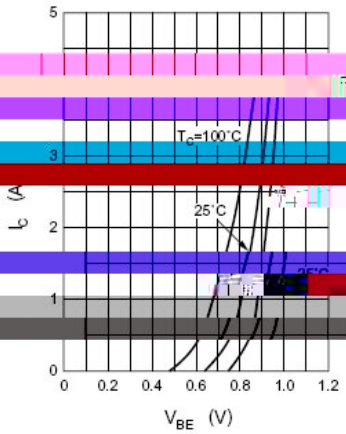
P_C — Ta



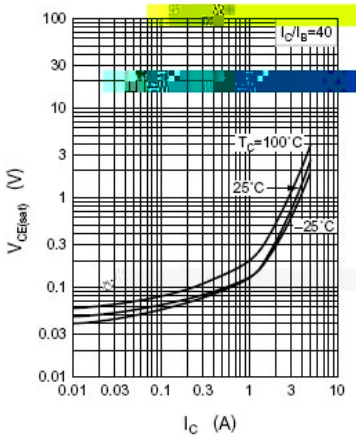
I_C — V_{CE}



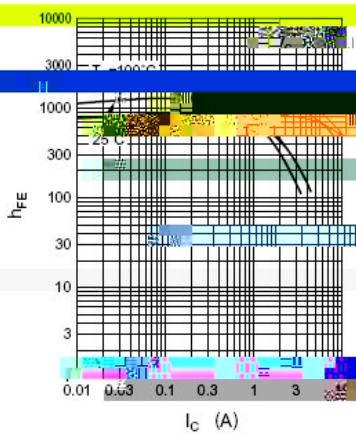
I_C — V_{BE}



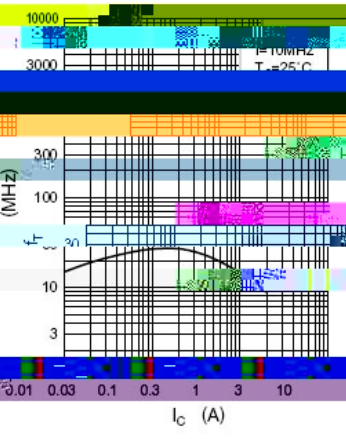
$V_{CE(sat)}$ — I_C



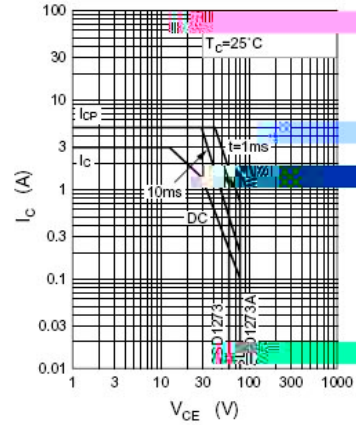
h_{FE} — I_C



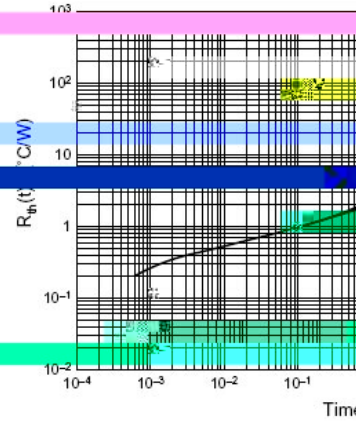
f_T — I_C



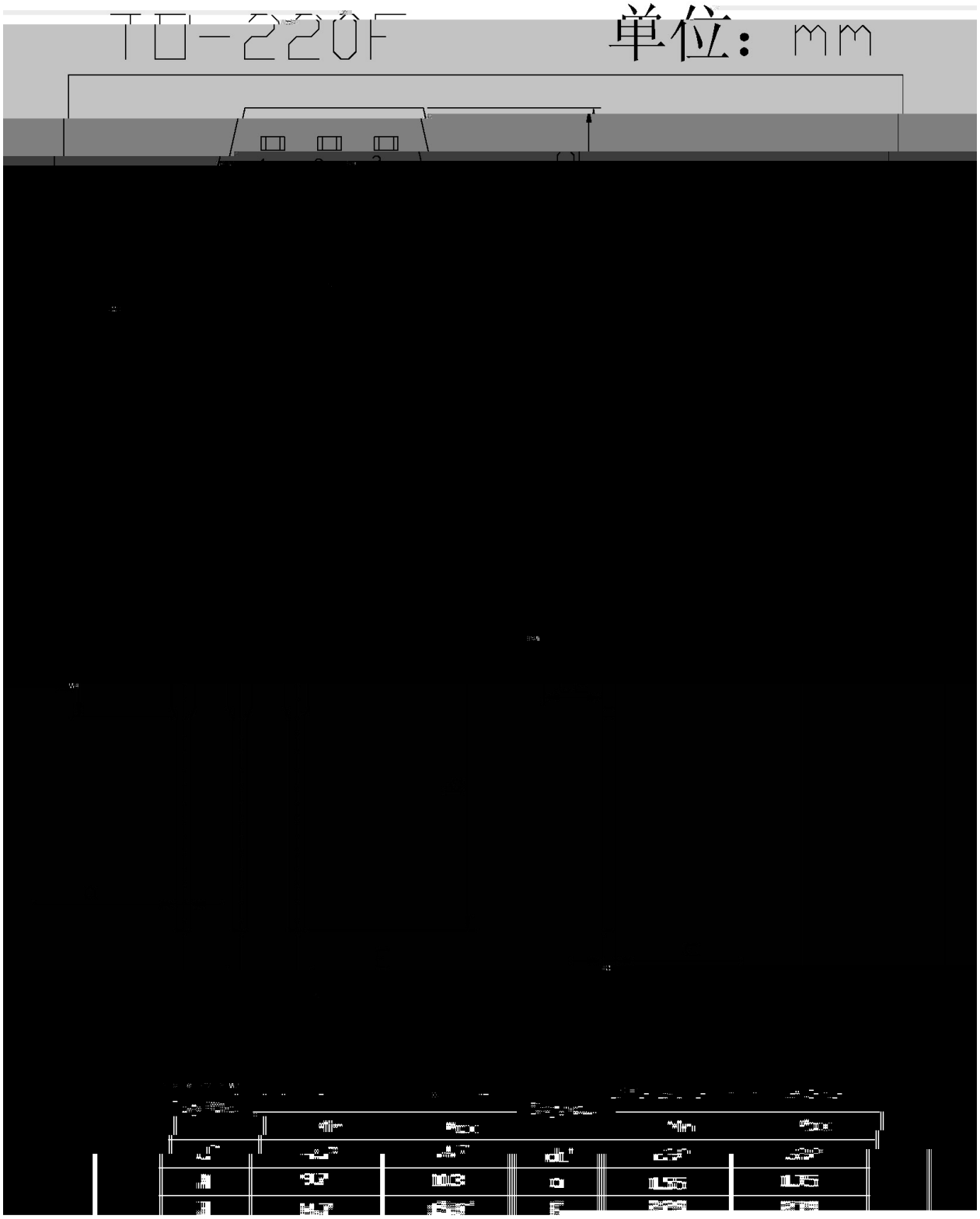
Area of safe operation (ASO)



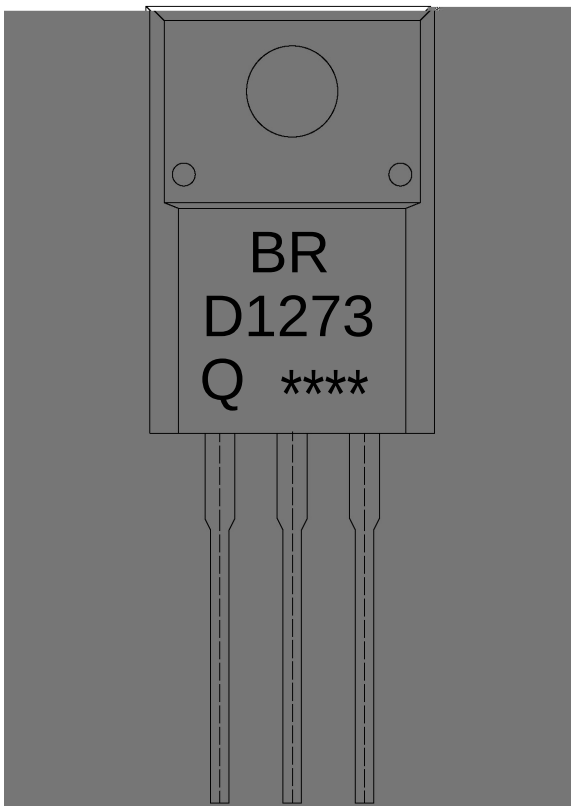
R_{th} — t



/ Package Dimensions



/ Marking Instructions



BR

D1273

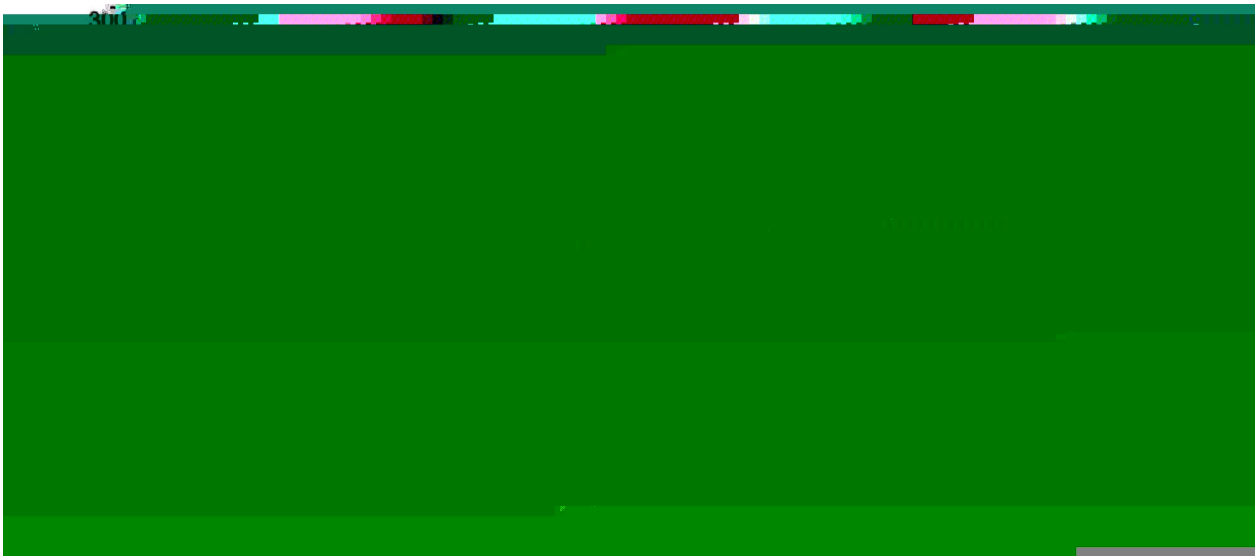
Q: h_{FE}

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Note:

BR:	Company Code.
D1273:	Product Type.
Q:	h_{FE} Classifications Symbol
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



										Note:	
1		25	150			60	90sec;			1.Preheating:25~150	, Time:60~90sec.
2		255±5					5±0.5sec;			2.Peak Temp.:255±5	, Duration:5±0.5sec.
3					2	10	/sec.			3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units			Dimension (unit mm^3)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	